

# NOT RECOMMENDED FOR NEW DESIGN USE DMP2067LVT



DMP2066LVT

#### P-CHANNEL ENHANCEMENT MODE MOSFET

## **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
-20V	45mΩ @ V <sub>GS</sub> = -4.5V	-4.5A
-20V	65mΩ @ V <sub>GS</sub> = -2.5V	-3.8A

# **Description**

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

## **Applications**

- General Purpose Interfacing Switch
- Power Management Functions

### **Features and Benefits**

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

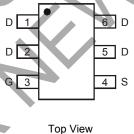
 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

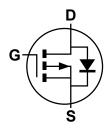
### **Mechanical Data**

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.015 grams (Approximate)





Pin-Out



**Equivalent Circuit** 

### Ordering Information (Note 4)

Part Number	Case	Packaging
DMP2066LVT-7	TSOT26	3,000/Tape & Reel
DMP2066LVT-13	TSOT26	10,000/Tape & Reel

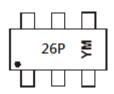
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**

#### TSOT26



26P = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/Test Site) Y or  $\overline{Y}$  = Year (ex: H = 2020) M = Month (ex: 9 = September)

Shanghai A/T Site

#### Date Code Kev

Date Code Key												
Year	2013		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	Α		Н	I	J	K	L	M	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

# **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		$V_{DSS}$	-20	V
Gate-Source Voltage		$V_{GSS}$	±8	V
Drain Current (Note 5) Continuous	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-4.5 -3.7	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I <sub>DM</sub>	-20	Α
Body-Diode Continuous Current (Note 5)		ls	-2.0	A

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P <sub>D</sub>	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	В	100	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ heta JA}$	74	C/VV
Total Power Dissipation (Note 6)		$P_{D}$	1.8	W
Thermal Decistor of Junction to Ambient (Note C)	Steady State	Б	70	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	R <sub>0JA</sub>	46	C/VV
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +150	°C

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:



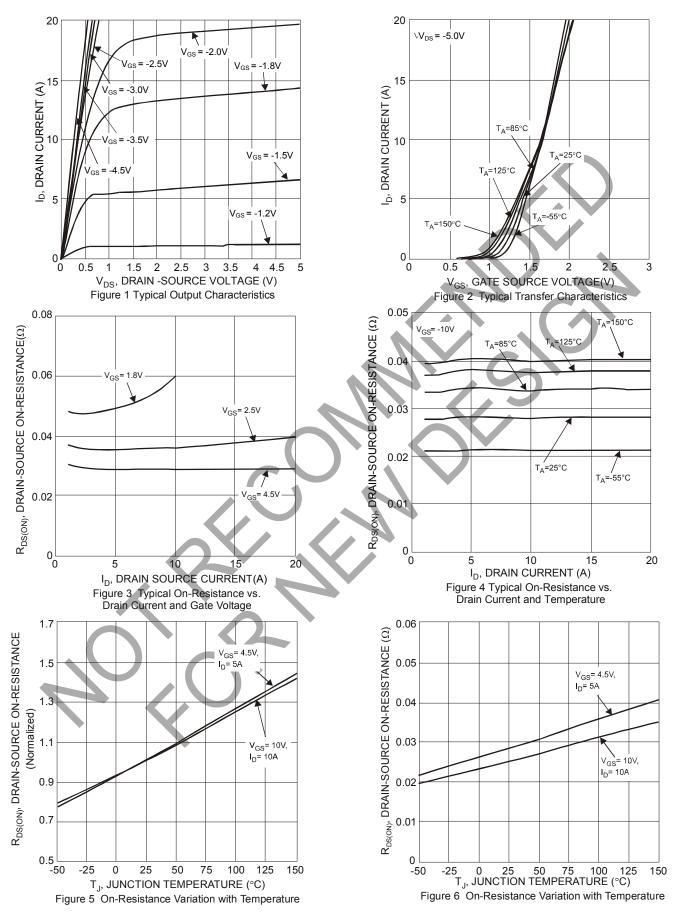
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
STATIC PARAMETERS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	٧	$I_D = -250 \mu A$ , $V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	lann			-1	μA	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V	
@ T <sub>J</sub> = +55°C (Note 8)	I <sub>DSS</sub>		_	-10	μΑ	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V	
Zero Gate Voltage Drain Current @T <sub>J</sub> = +150°C (Note 8)	I <sub>DSS</sub>	_	_	-100	μΑ	$V_{DS} = -16V, V_{GS} = 0V$	
Gate-Body Leakage Current	I <sub>GSS</sub>	_	_	±100	nA	$V_{DS} = 0V$ , $V_{GS} = \pm 8V$	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	_	-1.5	٧	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance	Paggan		25	45	mΩ	$V_{GS}$ = -4.5V, $I_D$ = -4.5A	
Static Drain-Source Off-Resistance	R <sub>DS(ON)</sub>		33	65	11152	$V_{GS} = -2.5V$ , $I_D = -3.8A$	
Static Drain-Source On-Resistance @ T <sub>J</sub> = +125°C (Note 8)	R <sub>DS ON)</sub>	_	_	72	mΩ	$V_{GS} = -4.5V$ , $I_D = -4.5A$	
Diode Forward Voltage	$V_{SD}$	-0.5	-0.72	-1.4	V	$I_S = -2.1A$ , $V_{GS} = 0V$	
On State Drain Current (Note 8)	I <sub>D(ON)</sub>	10	_		Α	$V_{DS} \le 5V$ , $V_{GS} = 4.5V$	
DYNAMIC PARAMETERS (Note 8)	•	•	•				
Input Capacitance	Ciss	_	1,496	2,990	pF		
Output Capacitance	Coss	_	130	260	pF	$V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	116	230	pF	11 - 1.0IVII 12	
Total Gate Charge	Q <sub>G</sub>	_	14.4	25			
Gate-Source Charge	Q <sub>GS</sub>		2.6	5	nC	$V_{DS} = -10V, V_{GS} = -4.5V,$	
Gate-Drain Charge	$Q_{GD}$	7-1	2.7	5.5		$I_D = -4.5A$	
Turn-On Delay Time	t <sub>D(ON)</sub>	17	8.5	30			
Rise Time	t <sub>R</sub>	1	11	60	<b>A</b> no	$V_{DS} = -5V$ , $V_{GS} = -4.5V$ ,	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	121	61	130	ns	$I_D = -1A, R_G = 6.0\Omega$	
Fall Time	t <sub>F</sub>		25	100			

7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing. Notes:









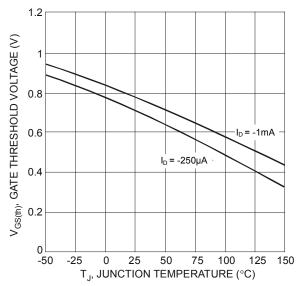
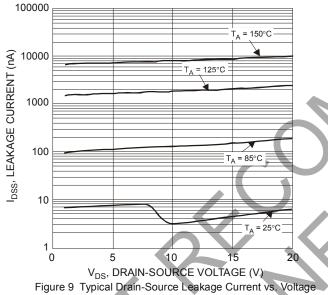
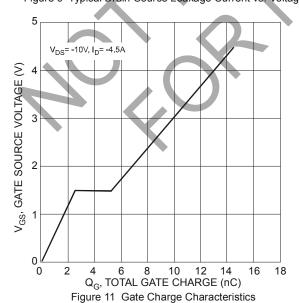
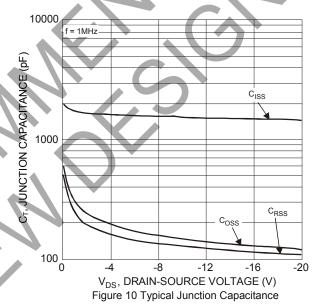


Figure 7 Gate Threshold Variation vs. Junction Temperature





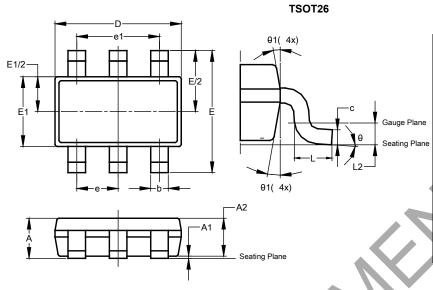
20 I<sub>S</sub>, SOURCE CURRENT (A) T<sub>A</sub>= 25°C 0.2 0.4 0.6 0.8 1
V<sub>SD</sub>, SOURCE-DRAIN VOLTAGE (V)
Figure 8 Diode Forward Voltage vs. Current 1.2





# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

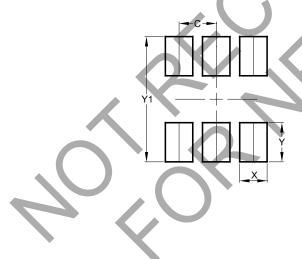


	TSOT26							
Dim	Min	Max	Тур					
Α	_	1.00	-					
A1	0.010	0.100						
A2	0.840	0.900	-					
D	2.800	3.000	2.900					
Е		2.800	BSC					
E1	1.500	1.700	1.600					
b	0.300	0.450	_					
С	0.120	0.200	-					
е		0.950	BSC					
e1		1.900	BSC					
L	0.30	0.50	_					
L2		0.250	BSC					
θ	°	8°	4°					
θ1	4°	12°	A					
All Dimensions in mm								

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
V1	3 100



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